

REMARKS/ARGUMENTS

This is in response to the Office Action mailed October 7, 2005.

Claims 1, 2, 4 through 8, 10 through 14, 16 through 20, and 22 through 24 are currently pending in the application.

Claims 3, 9, 15, and 21 have been canceled.

Claim 19 is objected to.

Claims 1 through 24 have been rejected.

Applicants have amended claims 1, 7, 13, and 19, and respectfully request reconsideration of the application as amended herein.

Information Disclosure Statement(s)

Applicants note the filing of Information Disclosure Statements herein on May 23, 2005, August 23, 2005, and October 4, 2005, and note that no copy of the PTO/SB/08's were returned with the outstanding Office Action. Applicants respectfully request that the information cited on the PTO/SB/08's be made of record herein.

Informality Objection to Claim 19

Claim 19 is objected to because of an insufficient antecedent basis for the "stress balancing layer" limitation in the claim. Claim 19 has been amended to use the stress balancing layer in the claim for consistent usage of claim terminology.

35 U.S.C. § 102(e) Anticipation Rejections

Anticipation Rejection Based on U.S. Patent Publication No. 2003/0017652 to Sakaki et al.

Claims 1 through 24 stand rejected under 35 U.S.C. § 102(e) as being anticipated by Sakaki et al. (U.S. Patent Publication No. 2003/0017652). Applicants respectfully traverse this rejection, as hereinafter set forth.

Applicants assert that a claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference.

Verdegaal Brothers v. Union Oil Co. of California, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The

identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

After carefully considering the cited prior art, the rejections, and the Examiner's comments, Applicants have amended the claimed invention to clearly distinguish over the cited prior art.

Turning to the cited prior art, the Sakaki et al. reference describes a resin for covering circuit formations on the surface of a semiconductor chip and a resin film for covering a back surface facing the circuit formation surface of the semiconductor chip. The resin covering the circuit formations and the resin film are described as made of a thermosetting resin of the epoxy group or a thermally hardened resin film having a carrier-tape. The Sakaki et al. does not describe, either expressly or inherently, either a stress-balancing layer or a force balancing layer comprising at least one of a metal, a metal alloy, a metallorganic material, a photoresist material, a multilayer material for balancing stresses in more than one direction, a tape material for balancing stresses in more than one direction, an adhesive material having reinforcement materials therein, a temporary adhesive material, a chemical vapor deposition material, and a physical vapor deposition material.

Applicants assert that the Sakaki et al. reference does not anticipate the claimed inventions of presently amended independent claims 1, 7, 13, and 19 under 35 U.S.C. § 102 because the Sakaki et al. reference does not identically describe, either expressly or inherently, each and every element of the claimed inventions in as complete detail as is contained in the claim. Applicants assert that the Sakaki et al. reference does not identically describe the elements of the inventions calling for "a stress-balancing layer covering at least a portion of the back side substantially balancing the stress caused by the passivation layer covering a portion of the integrated circuit, the stress-balancing layer comprising at least one of a metal, a metal alloy, a metallorganic material, a photoresist material, a multilayer material for balancing stresses in more than one direction, a tape material for balancing stresses in more than one direction, an adhesive material having reinforcement materials therein, a temporary adhesive material, a chemical vapor deposition material, and a physical vapor deposition material", "a stress-balancing layer covering at least a portion of the back side, the stress-balancing layer for balancing a portion of the front side stress with a generally equivalent back side stress, the stress-

balancing layer comprising at least one of a metal, a metal alloy, a metallorganic material, a photoresist material, a multilayer material for balancing stresses in more than one direction, a tape material for balancing stresses in more than one direction, an adhesive material having reinforcement materials therein, a temporary adhesive material, a chemical vapor deposition material, and a physical vapor deposition material”, and “a force-balancing layer covering at least a portion of the back side, the force-balancing layer for balancing a portion of the force on the front side, the force-balancing layer comprising at least one of a metal, a metal alloy, a metallorganic material, a photoresist material, a multilayer material for balancing stresses in more than one direction, a tape material for balancing stresses in more than one direction, an adhesive material having reinforcement materials therein, a temporary adhesive material, a chemical vapor deposition material, and a physical vapor deposition material”. Applicants assert that the Sakaki et al. reference merely describes the use of a thermosetting resin film 2 or a thermally hardened resin film having a carrier-tape bonded to a back surface 1Y facing the circuit formation surface 1X of the semiconductor chip 1 so as to cover the back surface 1 Y.

Applicants assert that such is not the claimed inventions of presently amended independent claims 1, 7, 13, and 19. Applicant asserts that a thermosetting resin film or a thermally hardened resin film having a carrier-tape bonded to a back surface thereof does not describe the inventions of presently amended independent claims 1, 7, 13, and 19 whatsoever.

Therefore, presently amended independent claims 1, 7, 13, and 19 are allowable as well as the dependent claims therefrom.

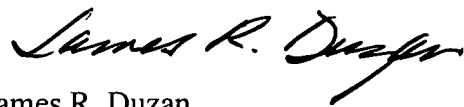
ENTRY OF AMENDMENTS

The amendments to claims 1, 7, 13, and 19 above should be entered by the Examiner because the amendments are supported by the as-filed specification and drawings and do not add any new matter to the application to clearly comply with the provisions of 35 U.S.C. § 132.

CONCLUSION

Claims 1, 2, 4 through 8, 10 through 14, 16 through 20, and 22 through 24 are believed to be in condition for allowance, and an early notice thereof is respectfully solicited. Should the Examiner determine that additional issues remain which might be resolved by a telephone conference, he is respectfully invited to contact Applicants' undersigned attorney.

Respectfully submitted,



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